

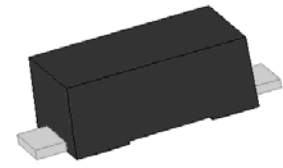


### DESCRIPTION:

The JEBxxD1F series are designed to protect sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events.

### FEATURES

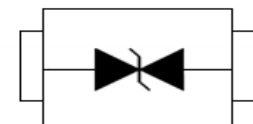
- ✧ 3500W to 6500W Peak pulse power dissipation on 1.2/50 $\mu$ s-8/20 $\mu$ s@2 $\Omega$  waveform
- ✧ For small surface mounted applications
- ✧ Response time is typically < 1ns
- ✧ Low clamping voltage
- ✧ Low leakage current
- ✧ RoHS compliant



SOD-123FL

### MAIN APPLICATIONS

- ✧ Cell phone handsets and accessories
- ✧ Personal digital assistants (PDA's)
- ✧ Notebooks, desktops, and servers
- ✧ Portable instrumentation



PIN Configuration

### PROTECTION SOLUTION TO MEET

- ✧ IEC61000-4-2 (ESD)  $\pm$ 30kV (air),  $\pm$ 30kV (contact)
- ✧ IEC61000-4-5 (Lightning) 200A (1.2/50 $\mu$ s-8/20 $\mu$ s@2 $\Omega$ )

### MECHANICAL CHARACTERISTICS

- ✧ SOD-123FL package
- ✧ Molding compound flammability rating : UL 94V-0
- ✧ Typical weight: 0.0168g/pcs
- ✧ Lead finish: lead free

**ABSOLUTE MAXIMUM RATINGS**( $T_A=25^{\circ}C$ , RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 1.2/50 $\mu$ s-8/20 $\mu$ s@2 $\Omega$ waveform	P <sub>PP</sub>	3500 to 6500	W
Peak pulse current on 1.2/50 $\mu$ s-8/20 $\mu$ s@2 $\Omega$ waveform	I <sub>PP</sub>	200	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V <sub>ESD</sub>	+/- 30 +/- 30	kV
Lead soldering temperature	T <sub>L</sub>	260 (10 sec.)	°C
Operating junction temperature range	T <sub>J</sub>	-55 to +150	°C
Storage temperature range	T <sub>STG</sub>	-55 to +150	°C

**ELECTRICAL CHARACTERISTICS** ( $T_A=25^{\circ}C$ )

Part Number	Marking	V <sub>R</sub>	I <sub>R@V<sub>R</sub></sub>	V <sub>BR@I<sub>T</sub></sub>		I <sub>T</sub>	P <sub>PP</sub> <sup>①</sup>	V <sub>C@I<sub>PP</sub></sub>	I <sub>PP</sub> <sup>②</sup>
				min(V)	max(V)				
Bi-Polar	Bi	V	$\mu$ A	min(V)	max(V)	mA	W	max(V)	A
JEB07D1F	07BF	7	1.0	8.0	10.0	1	3500	18.0	200
JEB12D1F	12BF	12	1.0	13.0	15.0	1	5500	28.0	200
JEB15D1F	15BF	15	1.0	16.5	19.5	1	6000	30.0	200
JEB18D1F	18BF	18	1.0	19.5	23.5	1	6500	33.0	200

① Peak pulse power dissipation (Surge waveform: 1.2/50 $\mu$ s-8/20 $\mu$ s@2 $\Omega$ )

② Peak pulse current (Surge waveform: 1.2/50 $\mu$ s-8/20 $\mu$ s@2 $\Omega$ )

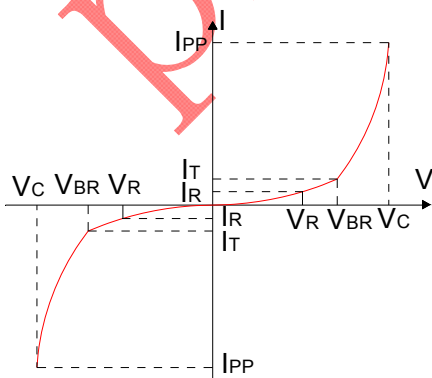
V<sub>R</sub>: Stand-off voltage -- Maximum voltage that can be applied

V<sub>C</sub>: Clamping voltage -- Peak voltage measured across the suppressor at a specified I<sub>PP</sub>

V<sub>BR</sub>: Breakdown voltage      I<sub>R</sub>: Reverse leakage current

**RATINGS AND V-I CHARACTERISTICS CURVES** ( $T_A=25^{\circ}C$ , unless otherwise noted)

**FIG.1: V- I curve characteristics (Bi-directional)**



**FIG.2: Pulse waveform (1.2/50 $\mu$ s)**

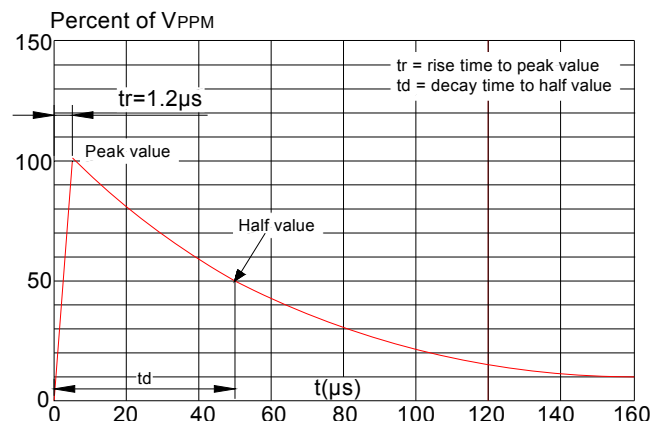


FIG.3: Pulse derating curve

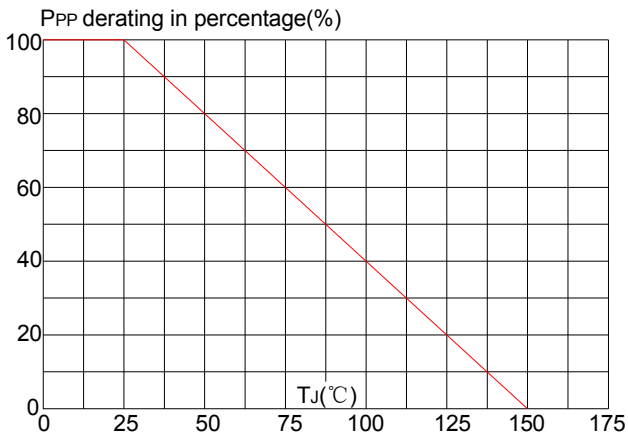
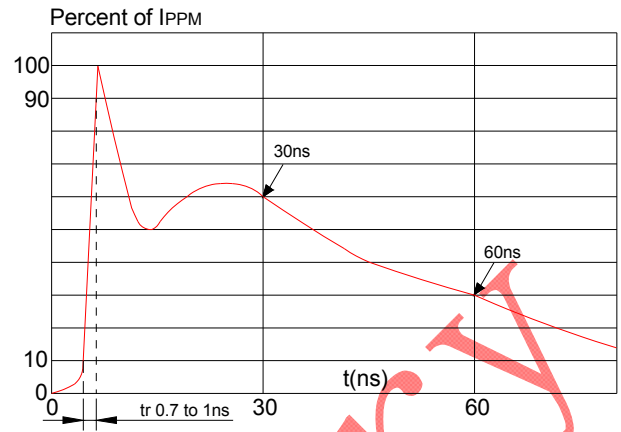
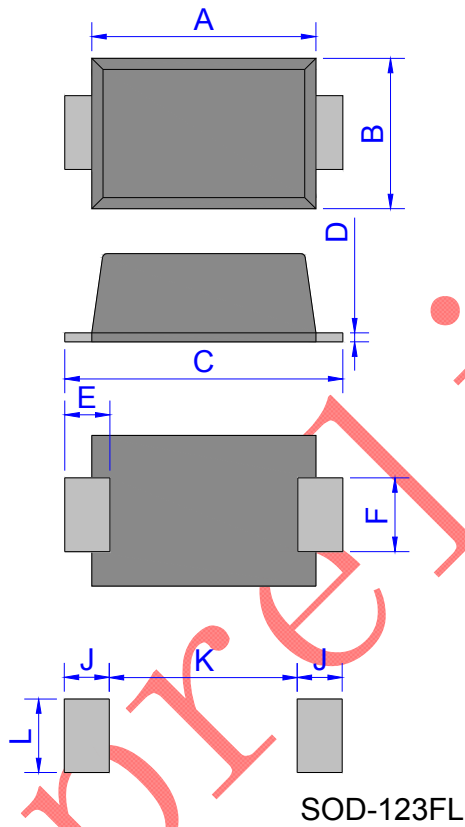


FIG.4: ESD clamping (30kV contact)

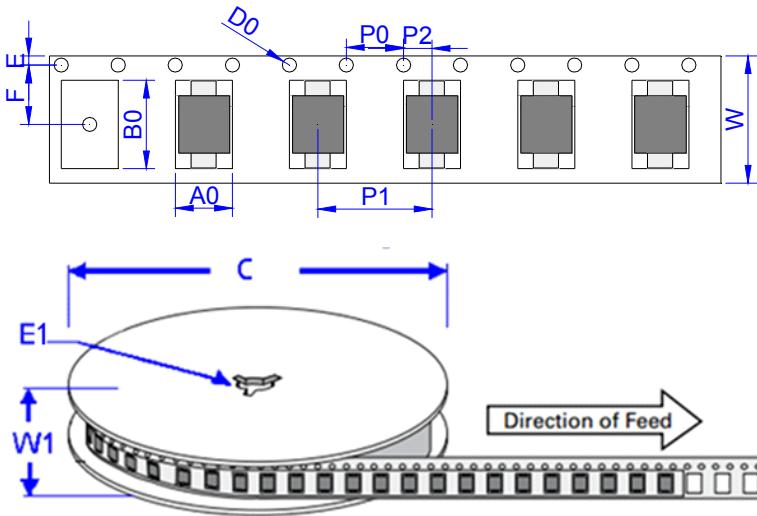


PACKAGE MECHANICAL DATA



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.60	3.00	0.102	0.118
B	1.60	2.00	0.063	0.079
C	3.45	3.95	0.136	0.156
D	0.10	0.25	0.004	0.01
E	0.3	0.9	0.012	0.035
F	0.80	1.20	0.031	0.047
G	0.95	1.35	0.037	0.053
J	1.30		0.051	
K		1.70		0.067
L	1.30		0.051	

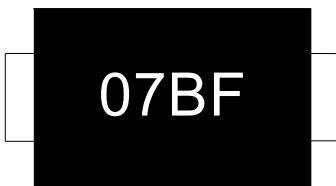
**TAPE AND REEL SPECIFICATION-SOD-123FL**



Ref.	Dimensions	
	Millimeters	Inches
A0	1.95 ± 0.3	0.077± 0.012
B0	3.95 ± 0.3	0.156 ± 0.012
C	178	7.0
D0	1.55 ± 0.1	0.061 ± 0.004
E	1.75 ± 0.2	0.069 ± 0.008
E1	13.3 ± 0.3	0.524± 0.012
F	3.50 ± 0.2	0.138 ± 0.008
P0	4.00 ± 0.2	0.157 ± 0.008
P1	4.00 ± 0.2	0.157 ± 0.008
P2	2.00 ± 0.2	0.079 ± 0.008
W	8.0± 0.2	0.315 ± 0.008
W1	11.5 ± 1.0	0.453 ± 0.039

PART No.	UNIT WEIGHT (g/PCS) typ.	PACKAGE	REEL (PCS)	DESCRIPTION
JEBxxD1F	0.0168	SOD-123FL	3000	7 inch reel pack

**MARKING CODE**



07BF : Device Marking Code

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